



10/777,804

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Docket No.: TESSERA 3.0-236 DIV
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Letters Patent of:
Beroz et al.

Patent No.: 7,205,659

Issued: April 17, 2007

For: ASSEMBLIES FOR TEMPORARILY
CONNECTING MICROELECTRONIC ELEMENTS
FOR TESTING AND METHODS THEREFOR

Certificate

DEC 19 2007

of Correction

Certificate of Correction Branch
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

**REQUEST FOR CERTIFICATE OF CORRECTION
PURSUANT TO 37 C.F.R. § 1.322**

Dear Sir:

Enclosed herewith is a Certificate of Correction with respect to the above-identified U.S. Patent.

The corrections indicated should be made as the application originally filed does not contain such errors. There is no requirement for payment of a fee since the errors were made by the Patent Office.

We look forward to early return of the Certificate of Correction duly certified.

Dated: December 10, 2007

Respectfully submitted,

By 

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**UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION**

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PATENT NO. : 7,205,659
APPLICATION NO. : 10/777,804
ISSUE DATE : April 17, 2007
INVENTOR(S) : Masud Beroz and David Light

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 13, line 45, "chip package chip, a" should read -- chip package, a -- .

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